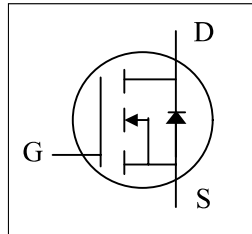


N-Channel Enhancement Mode Power MOSFET

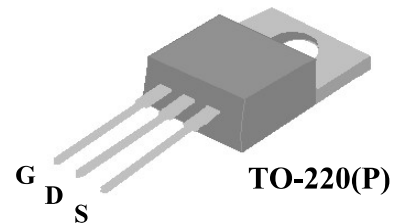
- ▼ Simple Drive Requirement
- ▼ Low On-resistance
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	55V
$R_{DS(ON)}$	7.8m $\Omega$
$I_D$	110A

## Description

AP3205 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.



The TO-220 package is widely preferred for all commercial-industrial through hole applications. The low thermal resistance and low package cost contribute to the worldwide popular package.

## Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	55	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ\text{C}$	Drain Current, $V_{GS}$ @ 10V	110	A
$I_D@T_C=100^\circ\text{C}$	Drain Current, $V_{GS}$ @ 10V	70	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	400	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	187.5	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	2.41	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	269	mJ
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	0.8	$^\circ\text{C}/\text{W}$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	62	$^\circ\text{C}/\text{W}$

N-Channel Enhancement Mode Power MOSFET

**Electrical Characteristics@T<sub>j</sub>=25°C(unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	55	-	-	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =62A	-	-	12	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2	-	4	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =62A	-	105	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =44V, V <sub>GS</sub> =0V	-	-	10	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =62A	-	97	155	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =44V	-	27	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =10V	-	46	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =28V	-	20	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =62A	-	125	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =1.5 Ω	-	35	-	ns
t <sub>f</sub>	Fall Time	V <sub>GS</sub> =10V	-	14	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	3900	6240	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V	-	600	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	365	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	1	2	Ω

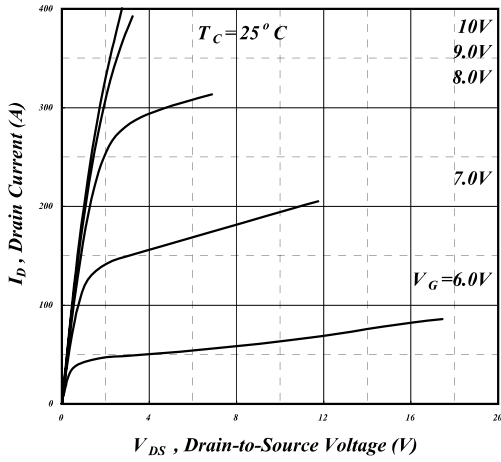
**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =62A, V <sub>GS</sub> =0V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =62A, V <sub>GS</sub> =0V,	-	50	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI/dt=100A/μs	-	80	-	nC

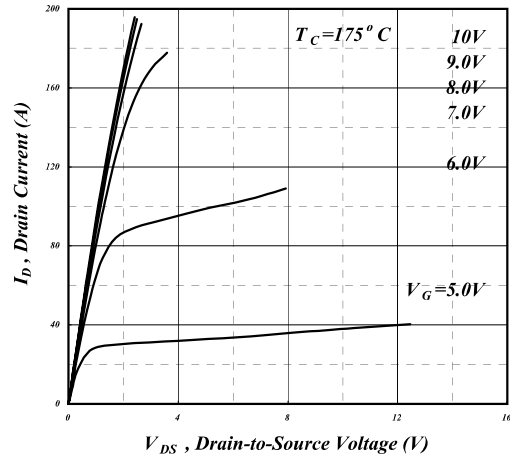
**Notes:**

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Starting T<sub>j</sub>=25°C , V<sub>DD</sub>=30V , L=0.14mH , R<sub>G</sub>=25 Ω

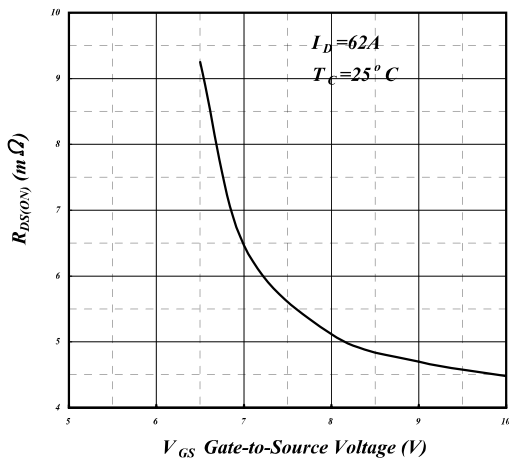
## N-Channel Enhancement Mode Power MOSFET



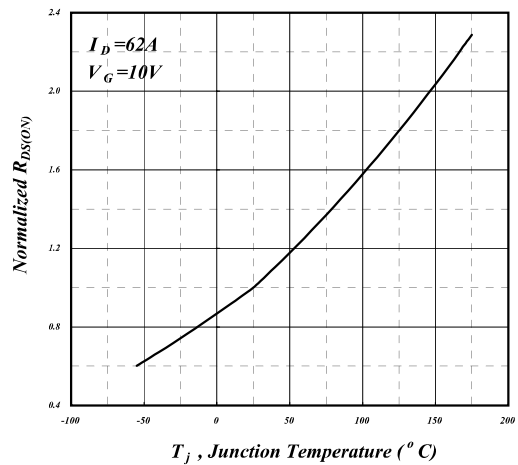
**Fig 1. Typical Output Characteristics**



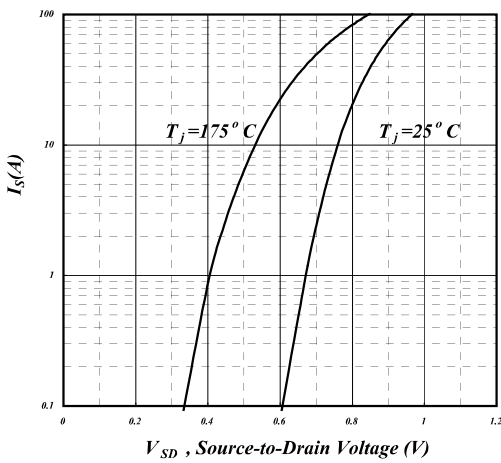
**Fig 2. Typical Output Characteristics**



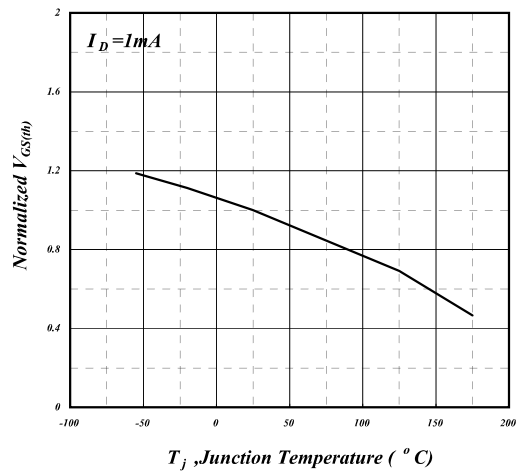
**Fig 3. On-Resistance v.s. Gate Voltage**



**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



**Fig 5. Forward Characteristic of Reverse Diode**



**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

## N-Channel Enhancement Mode Power MOSFET

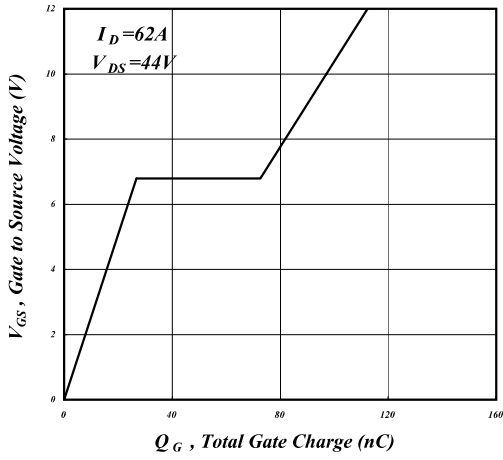


Fig 7. Gate Charge Characteristics

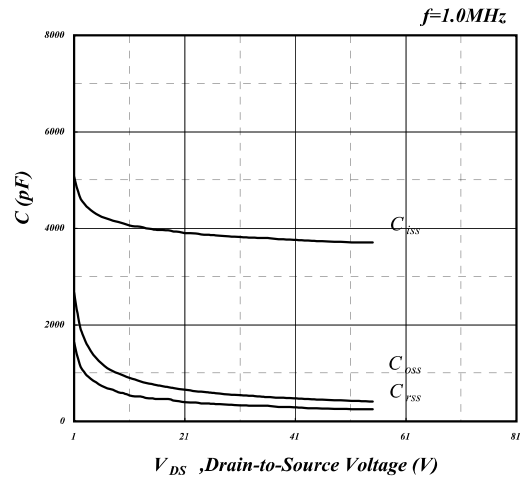


Fig 8. Typical Capacitance Characteristics

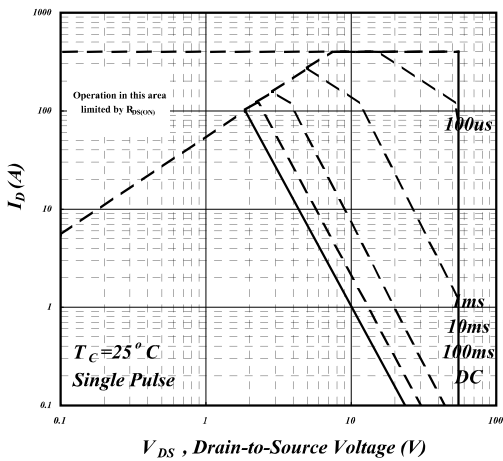


Fig 9. Maximum Safe Operating Area

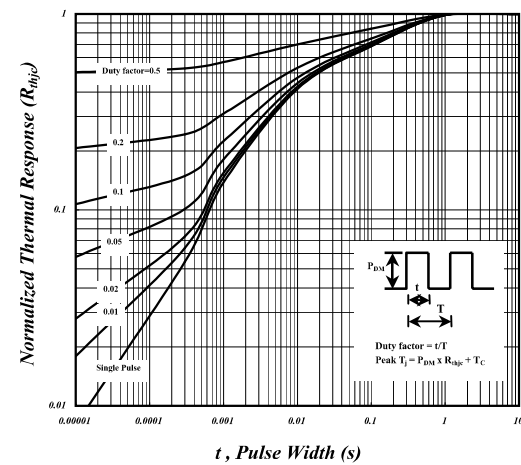


Fig 10. Effective Transient Thermal Impedance

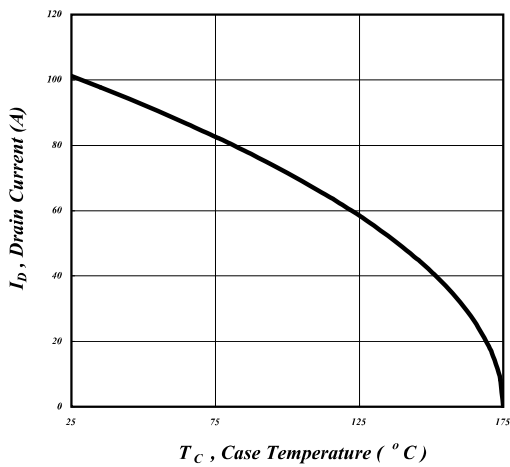


Fig 11. Drain Current v.s. Case Temperature

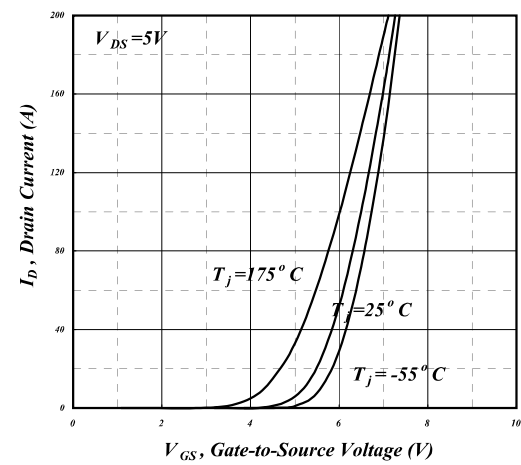
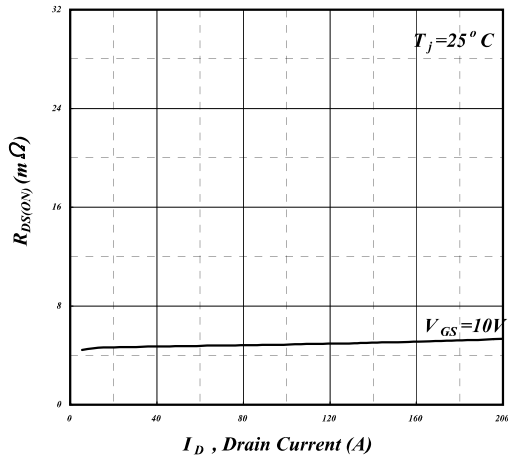
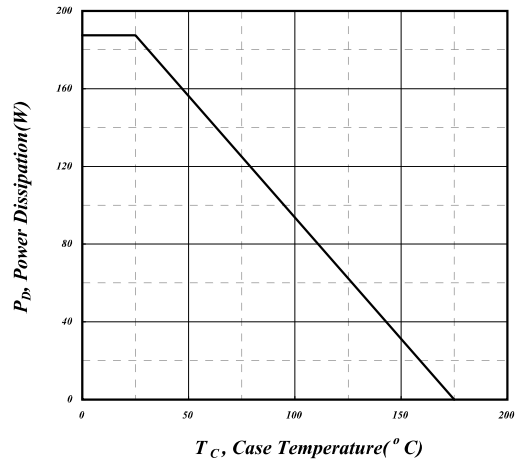


Fig 12. Transfer Characteristics

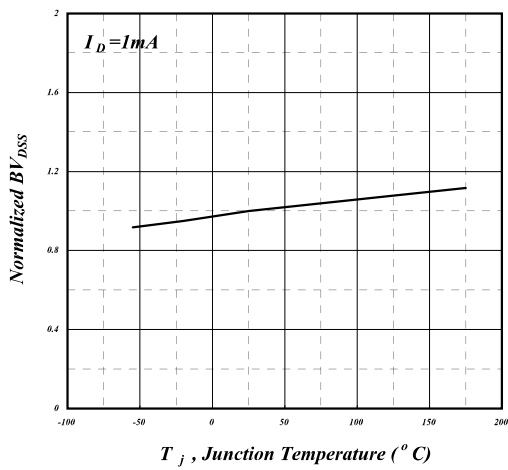
N-Channel Enhancement Mode Power MOSFET



**Fig 13. Typ. Drain-Source on State Resistance**



**Fig 14. Total Power Dissipation**



**Fig 15. Normalized  $BV_{DSS}$  v.s. Junction**

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